

IMPROVEMENTS FOR THIN-FILM TAPE HEAD PROCESSES

ABSTRACT

A plurality of apparatuses and methods are provided for improving the manufacture and operational characteristics of thin magnetic film heads. First provided is an apparatus and method for bonding a beam and a magnetic head with optimal precision. Also included is a saw apparatus capable of dicing magnetic heads on an associated wafer in a manner that affords a planar operating surface on the magnetic head. Still yet, a specific head structure is provided which has single a groove that affords all of the benefits of the prior art head structures, but with only one action required during the thin-film head manufacturing process.